

Call for Application for Sponsorship

The 4th Asia–Pacific Conference on Physical Modelling in Geotechnics (ACPMG 2024), Abu Dhabi, United Arab Emirates

11th – 13th December 2024

Introduction

The 4th Asia-Pacific Conference on Physical Modelling in Geotechnics (ACPMG 2024) in Abu Dhabi, United Arab Emirates, from 11th to 13th December 2024.

The conference organised by the Technical Committee on Physical Modelling (TC104) of the International Society of Soil Mechanics and Geotechnical Engineering (ISSMGE) and aims to provide an up-to-date overview of the latest developments in multi-scale physical modelling within the following themes:

- New facilities, new equipment, and measuring techniques
- Resilient Geotechnical Infrastructure
- Sustainability in Geotechnical Systems
- Energy geo-structures and foundation systems
- Application of Machine Learning/Artificial Intelligence in Geotechnical Engineering

Details for this Event shall be referred to the website: [ACPMG 2024](#)

Invitation to Apply for Sponsorship

HKIE GDC is considering to sponsor up to 2 engineers to join this Event. Subsidy on registration fee up to HK\$5,000 will be offered to the successful applicants individually. To qualify, applicants shall satisfy the following basic criteria:

- i. Be a member of the Hong Kong Institution of Engineers, of whatever class;
- ii. Submit your current curriculum vitae;
- iii. Prepare a written report on the Event.

The successful applicants may be invited by the GDC to share their experience of this Event which will be held in Hong Kong after the Event.

The applications will be assessed by the GDC based on the relevancy of this Event to their career development. The successful applicants will be notified no later than 2nd December 2024. All applications or enquiries shall be submitted by 25th November 2024 to Ir Ray CHAN, Tel: 9687 3131, email: raychan@arecongroup.com.

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Application for Sponsorship

Personal Particulars	
Name: _____ (in English)	_____ (in Chinese)
HKIE/HKGES Membership No:	HKIE/HKGES Membership Class:
Organization:	Capacity:
Correspondence Address:	
Tel:	Mobile:
Fax:	Email:

Academic/Professional Qualifications
Academic Qualifications:
Professional Qualifications:

Working Experience		
Name of Organisation:	Capacity:	Period:

Record of Services to HKIE / HKGES and Other Organizations		
Name of board/committee:	Capacity:	Period:

The personal data provided by means of this curriculum vitae form will be used as reference for the Institution to assess the merit of sponsoring the application.
In accordance with Section 18 and 22 and Principle 6 of Schedule 1 of the Personal Data (Privacy) Ordinance, you have the rights to request access to and request the correction of the data provided.